

PCN20250414001.1
Qualification of additional Assembly sites for select UxQFN devices
Change Notification / Sample Request

Date: April 14, 2025

To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20250414001.1**Attachment: 1****Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS622310DRYT	TPS622310DRYT
TPS622316DRYT	TPS622316DRYT
TPS3779DDRYT	TPS3779DDRYT
TPS62230DRYR	TPS62230DRYR
TPS62234DRYR	TPS62234DRYR
TPS62239DRYR	NULL
TPS62230DRYT	TPS62230DRYT
TPS62233DRYT	TPS62233DRYT
TPS62235DRYT	TPS62235DRYT
TPS62239DRYT	TPS62239DRYT
SN74LXCH1T45DRYR	NULL
TPS622318DRYT	TPS622318DRYT
SN74LXC1T45DRYR	NULL
ESD224DQAR	ESD224DQAR
TS3USB30ERSWR	TS3USB30ERSWR
TPS3780ADRYT	TPS3780ADRYT
TPS3780DDRYT	TPS3780DDRYT

Technical details of this Product Change follow on the next page(s).

PCN Number:	PCN#20250414001.1	PCN Date:	April 14, 2025
Title:	Qualification of additional Assembly sites for select UxQFN devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	July 13, 2025	Sample requests accepted until:	June 13, 2025*

***Sample requests received after June 13, 2025 will not be supported.**

Change Type:

<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Material
<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Process
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Fab Site
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Material
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the qualification of additional Assembly sites for devices listed below in the product affected section. Construction information and all assembly sites are as follows:

UxQFN Build Sites	
Assembly Sites	ASEN, CARZ, CIRTEK, HNA, JCETJY, UTL1/UTL3, CDAT
Mount Compound	SID#1400329101
	SID#1400336111
	SID#1400397101
	SID#1400238112
	SID#1400128131
	SID#443156
	4207123
	SID#PZ0031
	4226215
Mold Compound	SID#120903003709
	SID#446645
	SID#CZ0140
	SID#1801512111
	SID#CZ0136
	4222198
Leadframe Finish	NiPdAu
Bond Wire (mil)	AU (0.6, 0.8, 1.0), CU (0.8)

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS

No Change

REACH

No Change

Green Status

No Change

IEC 62474

No Change

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
ASEN	ASN	CHN	Suzhou
CARZ	CSZ	CHN	Jiangsu
CIRTEK	CTK	PHL	Binan
HNA	HNT	THA	Ayutthaya
JCETJY	JCE	CHN	Jiangyin
UTL1	NSE	THA	Bangkok
UTL3	UT3	THA	Bangpakong
CDAT	CDA	CHN	Chengdu

Sample product shipping label (not actual product label)



Product Affected:

ESD224DQAR	TPS3780ADRYT	TPS622313DRYT	TPS62234DRYT
SN74AXCH1T45DRY2	TPS3780BDRYR	TPS622315DRYR	TPS62235DRYR
SN74AXCH1T45DRYR	TPS3780BDRYT	TPS622315DRYT	TPS62235DRYT
SN74LXC1T45DRYR	TPS3780CDRYR	TPS622316DRYR	TPS62236DRYR
SN74LXCH1T45DRYR	TPS3780CDRYT	TPS622316DRYT	TPS62236DRYT
TPS3779ADRYR	TPS3780DDRYR	TPS622317DRYR	TPS62238DRYR
TPS3779ADRYT	TPS3780DDRYT	TPS622317DRYT	TPS62238DRYT
TPS3779BDRYR	TPS62230DRYR	TPS622318DRYR	TPS62239DRYR
TPS3779BDRYT	TPS62230DRYT	TPS622318DRYT	TPS62239DRYT
TPS3779CDRYR	TPS622310DRYR	TPS622319DRYR	TS3USB30ERSWR
TPS3779CDRYT	TPS622310DRYT	TPS622319DRYT	TS5USBA224RSWR
TPS3779DDRYR	TPS622312DRYR	TPS62233DRYR	
TPS3779DDRYT	TPS622312DRYT	TPS62233DRYT	
TPS3780ADRYR	TPS622313DRYR	TPS62234DRYR	

UxQFN Qualification Report

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	CDAT TMUXHS221NKG	ASEN TCAL6408RSV
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 284 hours Or 1000 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/86/0	3/86/0 (BQ298000RUG)
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	CARZ TPS3897ADRY DAC7551ZTDRNRQ1 AFE881H1RRU	UTL1 INA199A1RSW INA210BIRSW ADS1115QNKS
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0
HAST/ THB	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (SN74AXC2T45DTM)	3/66/0
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	JCETJY CD3285A0RSV	UTL3 TS3USB221ERSE TS3USB221RSE TS3USB221ARSE INA210AIRSW
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/135/0	3/165/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	HNA TS3A44159RSV	CIRTEK TPD4EUSB30DQA
TC	Temperature Cycling -85/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/135/0	3/165/0
UHAST /AC	Unbiased HAST,130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0
MQ	Manufacturability	-	Pass	Pass

TMUXHS221NKG, TCAL6408RSV, INA210BIRSW, INA199A1RSW, TS3USB221ERSE, TS3USB221RSE, TS3USB221ARSE, INA210AIRSW TPS3897ADRY, and CD3285A0RSV, TPD4EUSB30DQA, TS3A44159RSV are qualified at L1-260C MSL rating
DAC7551ZTDRNRQ1, AFE881H1RRU, ADS1115QNKS qualified at L2-260C MSL rating

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable
- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com>

Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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